

22. (Twice Amended) An electronic component comprising:
a substrate with a plurality of contact nodes; and
a plurality of free-standing resilient interconnection elements coupled to the substrate in such a manner that a base of an interconnection element electrically contacts a corresponding one of the contact nodes and an interconnection element comprises:

a first element material adapted to be coupled to a substrate, and
a second different element material coupled to the first element material,
wherein one of the first element material and the second element material comprises a material having a transformable property such that upon transformation, a shape of the interconnection element is modified, wherein the one of the first element material and the second element material comprises a shape memory alloy.

48. (Three Times Amended) An assembly comprising:
a first substrate having a plurality of first contact nodes formed on the first substrate and a plurality of free-standing resilient interconnection elements coupled to the first substrate in such a manner that a base of an interconnection element electrically contacts a corresponding one of the first contact nodes; and

a second substrate having a plurality of second contact nodes,
wherein the interconnection element comprises:
a first element material adapted to be coupled to the first substrate, and
a second different element material coupled to the first element material,
and one of the first element material and the second element material comprises a material having a transformable property such that upon transformation, a geometric shape of the interconnection element is modified,

wherein the interconnection element has a portion thereof which is capable of moving to a first position in which the interconnection element is in contact with one of the plurality of second contact nodes.

76. (Three Times Amended) A system for contacting an electronic device including an assembly comprising:

a first substrate having a plurality of first contact nodes formed on the first substrate and a plurality of free-standing resilient interconnection elements coupled to the first substrate in such a manner that a base of an interconnection element electrically contacts a corresponding one of the first contact nodes; and

a second substrate having a plurality of second contact nodes,
wherein the interconnection element comprises:

a first element material adapted to be coupled to the first substrate, and

c4 a second different element material coupled to the first element material,
and one of the first element material and the second element material comprises a material having a transformable property such that upon transformation, a shape of the interconnection element is irreversibly modified, wherein the one of the first element material and the second element material comprises a shape memory alloy,
and

wherein the interconnection element has a portion thereof which is capable of moving to a first position in which the interconnection element is in contact with one of the plurality of second contact nodes.
